

# **Product Preview**

# 600V 380m $\Omega$ Superjunction MOSFET



#### Features

- Advanced superjunction technology
- Ultra-low on-resistance and gate-charge
- RoHS compliant
- 100% avalanche tested

# Applications

- Server/PC
- Telecom
- LED Applications



Product Summary				
V <sub>DS</sub>	600V			
Rds(on)	318 mΩ (Typ.)			
	380 mΩ (Max.)			
lD	9.6 A			





### **Ordering Information**

Part Number	Marking	Package	Packaging
JCG60R380S	CG60R380S	TO-220MF	Tube



# **Absolute Maximum Ratings**

Parameter	Symbol	Limit	Unit
Drain-to-Source Voltage	V <sub>DSS</sub>	600	V
Gate-to-Source Voltage	V <sub>GSS</sub>	±30	V
Continuous Drain Current, Silicon Limited ( $T_c = 25^{\circ}C$ ) <sup>(1),(2)</sup>	lo	9.6	А
Continuous Drain Current, Silicon Limited ( $T_c = 100^{\circ}C$ ) <sup>(1),(2)</sup>	ID	6.0	А
Pulsed Drain Current <sup>(3)</sup>	Ідм	28.8	А
Avalanche Energy, Single Pulse <sup>(4)</sup>	Eas	40	mJ
Power Dissipation (T <sub>c</sub> = 25°C)	PD	28	W
Avalanche Current <sup>(4)</sup>	I <sub>AS</sub>	2.5	А
Junction Temperature	T,	-55 to 150	°C
Storage Temperature	T <sub>STG</sub>	-55 to 150	°C

### **Thermal Characteristics**

Parameter	Symbol	Max	Unit
Junction-to-Ambient Thermal Resistance	R <sub>θJA</sub>	62.5	°C/W
Junction-to-Case Thermal Resistance	Rejc	4	C/ W

# Static Electrical Characteristics <sup>(5)</sup>

Parameter	Symbol	Test Conditions	Min	Тур	Max	Unit
Drain-to-Source Breakdown Voltage	BV <sub>DSS</sub>	V <sub>GS</sub> = 0 V, I <sub>D</sub> = 1 mA	600	-	-	M
Gate Threshold Voltage	V <sub>GS(TH)</sub>	$V_{DS} = V_{GS}$ , $I_D = 0.8$ mA	2.5	-	4.5	V
Drain-to-Source Leakage Current	I <sub>DSS</sub>	$V_{DS} = 600 \text{ V}, \text{ V}_{GS} = 0 \text{ V}$	-	-	1	μA
Gate-to-Source Leakage Current	Igss	$V_{DS} = 0V, V_{GS} = \pm 30V$	-	-	±100	nA
Drain-to-Source On-Resistance	R <sub>DS(ON)</sub>	$V_{GS}$ = 10 V, I <sub>D</sub> = 4.0 A	-	318	380	mΩ
Gate Resistance	RG	f = 1 MHz, open drain	-	1.0	-	Ω

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# Dynamic Electrical Characteristics <sup>(5)</sup>

Parameter	Symbol	Test Conditions	Min	Тур	Max	Unit
Total Gate Charge	Qg	V <sub>GS</sub> = 10 V,	-	15.5	-	
Gate-to-Source Charge	Q <sub>gs</sub>	V <sub>DS</sub> = 400 V,	-	3	-	nC
Gate-to-Drain Charge	$Q_{gd}$	I <sub>D</sub> = 4.0 A	-	8	-	
Turn-On Delay Time	td(on)	V <sub>GS</sub> = 10 V,	-	8	-	
Rise Time	tr	V <sub>DS</sub> = 400 V,	-	7	-	
Turn-Off Delay Time	t <sub>d(off)</sub>	I <sub>D</sub> = 4.0 A,	-	30	-	ns
Fall Time	tr	R <sub>G</sub> = 10 Ω	-	8	-	
Input Capacitance	Ciss		-	628	-	
Output Capacitance	C <sub>oss</sub>	V <sub>GS</sub> = 0 V, f = 250 kHz,	-	20	-	рF
Reverse Transfer Capacitance	Crss	V <sub>DS</sub> = 400 V		3		
Effective Output Capacitance,	6	$V_{GS} = 0 V, V_{DS} = 0 V to$		220		<b>а</b> Г
Energy Related <sup>(6)</sup>	Co(er)	400 V		239		pF
Effective Output Capacitance,	C	$V_{GS} = 0 V, V_{DS} = 0 V to$		20		~ <b>Г</b>
Time Related <sup>(7)</sup>	Co(tr)	400 V		30		pF

#### Source Drain Characteristics <sup>(5)</sup>

Parameter	Symbol	Test Conditions	Min	Тур	Max	Unit
Diode Forward Voltage	V <sub>SD</sub>	$V_{GS}$ = 0 V, I <sub>F</sub> = 4.0 A	-	-	1.2	V
Reverse Recovery Time	t <sub>rr</sub>	V <sub>R</sub> = 400 V,	-	221	-	ns
Reverse Recovery Charge	Qrr	$I_F = 4.0 A_{,}$	-	1.8	-	μC
Peak Reverse Recovery Current	I <sub>rrm</sub>	di⊧/dt = 100 A/us	-	-	-	А

(1) Limited by maximum  $T_{J max}$ . Maximum duty cycle D=0.75.

(2) Rated according to  $R_{\theta JA}$ .

(3) Repetitive rating: pulse-width limited by maximum junction temperature.

(4)  $T_A = 25^{\circ}C$ ,  $R_G = 25\Omega$ ,  $I_{AS} = 2.5 A$ .

(5) T<sub>J</sub> = 25°C unless otherwise specified.

(6)  $C_{o(er)}$  is an equivalent capacitance that provides the same stored energy as  $C_{oss}$  while  $V_{DS}$  is changing from 0 to 400 V.

(7)  $C_{o(tr)}$  is an equivalent capacitance that provides the same charging time as  $C_{oss}$  while  $V_{DS}$  is changing from 0 to 400 V.

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# **Electrical Characteristics Diagrams**





Fig. 2 Typical transfer characteristics



Fig. 3 Typical capacitance characteristics



Fig. 4 Typical gate charge characteristics





Fig. 7 Typical power dissipation









Temperature



## **Test Circuits and Waveforms**



Fig. 1 Inductive switching time test circuit & waveforms



Fig. 2 Gate charge test circuit & waveform



Fig. 3 Peak diode recovery dv/dt test circuit & waveforms





Fig. 4 Unclamped inductive switching test circuit & waveforms



# Package Drawing





evanot		MM				
SYMBOL	MIN	NOM	MAX			
E	9.96	10.16	10.36			
Α	4.50	4.70	4.90			
A1	2.34	2.54	2.74			
A2	0.30	0.45	0.60			
A4	2.56	2.76	2.96			
С	0.40	0.50	0.65			
c1	1.20	1.30	1.35			
D	15.57	15.87	16.17			
H1		6. 70REF				
е		2.54BSC				
L	12.68	12.98	13.28			
L1	3.03	3.23	3.43			
ΦP	3.03	3.18	3.38			
ΦΡ3	3.15	3.45	3.65			
F3	3.15	3.30	3.45			
G3	1.25	1.35	1.55			
b1	1.18	1.28	1.43			
b2	0.70	0.80	0.95			

**TO-220MF** 

**Equivalent Circuit** 



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#### **Revision history of JCG60R380S specification**

Version	Change Items	Effective Date
1.00	Initial release.	12-Jan-22



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